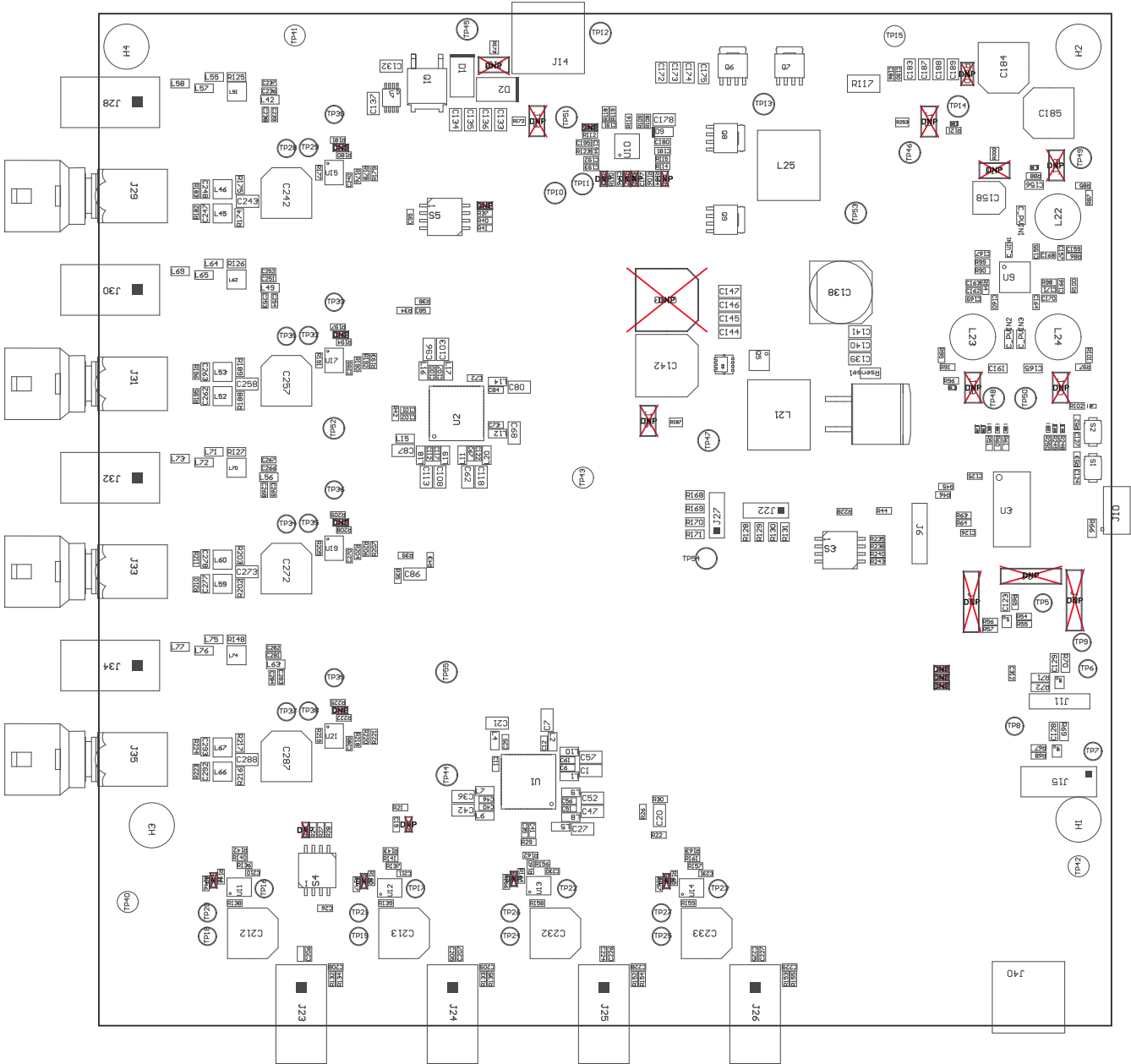


Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
Z22 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
Z23 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z24 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



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